



9/7/06

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Docket No. 51565  
Express Mail Label No. EV755070212US

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT: Seita et al.  
SERIAL NO. 10/696,552 GROUP: 1775  
FILED: October 29, 2003 EXAMINER: M. Lavilla  
FOR: FORMALDEHYDE-FREE ELECTROLESS COPPER PLATING  
PROCESS AND SOLUTION FOR USW IN THE PROCESS

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Applicants are in receipt of the Office Action dated October 5, 2006. Please amend the above-identified application as follows.

A listing of pending claims begins on page 2 of this paper.

Remarks being on page 5 of this paper.